



## General Description

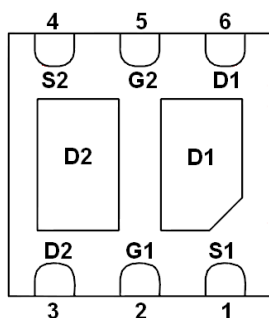
AFP2925W, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

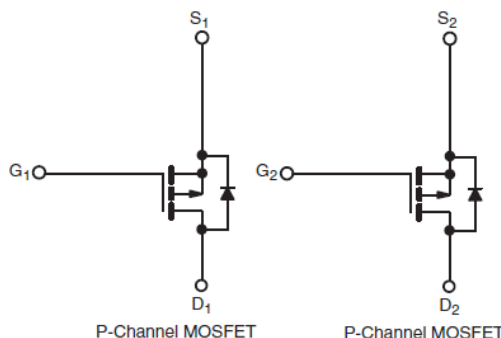
## Features

- $I_D = -3.6A, R_{DS(ON)} = 50m\Omega @ V_{GS} = -4.5V$
- $I_D = -3.2A, R_{DS(ON)} = 63m\Omega @ V_{GS} = -2.5V$
- $I_D = -1.2A, R_{DS(ON)} = 84m\Omega @ V_{GS} = -1.8V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN2X2-6L package design

## Pin Description ( DFN2X2-6L )

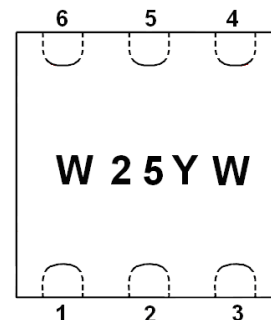


BOTTOM VIEW



P-Channel MOSFET

P-Channel MOSFET



TOP VIEW

## Application

- Charger Switches and Load Switches for Portable Devices
- DC/DC Converters

## Pin Define

Pin	Symbol	Description
1	S1	Source1
2	G1	Gate1
3	D2	Drain2
4	S2	Source2
5	G2	Gate2
6	D1	Drain1

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP2925WFN226RG	W25YW	DFN2X2-6L	Tape & Reel	4000 EA

※ W25 parts code

※ Y year code

※ W week code ( A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52 )

※ AFP2925WFN226RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



### Absolute Maximum Ratings

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	-20	V
Gate –Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>C</sub> =25°C	-4.5
		T <sub>C</sub> =70°C	-4.5
Pulsed Drain Current	I <sub>DM</sub>	-15	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	-1.6	A
Power Dissipation	P <sub>D</sub>	T <sub>C</sub> =25°C	7.8
		T <sub>C</sub> =70°C	5.0
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	52	°C/W
Thermal Resistance-Junction to Case(Drian)	R <sub>θJC</sub>	12.5	

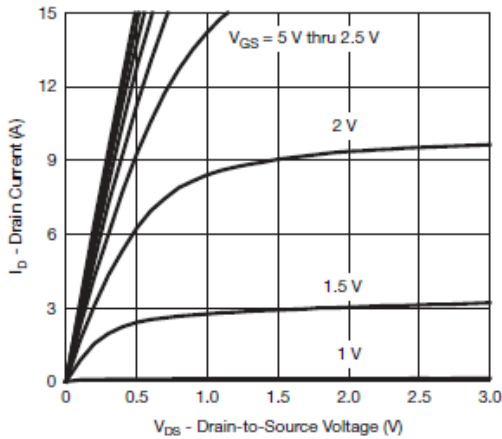
### Electrical Characteristics

(T<sub>A</sub>=25°C Unless otherwise noted)

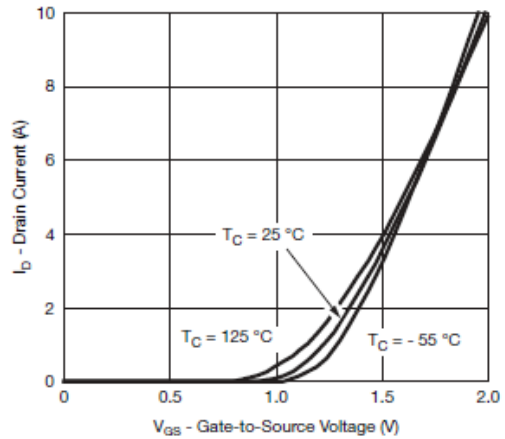
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.4		-1.0	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V			±10	uA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			-10	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ -5V, V <sub>GS</sub> =-4.5V	-10			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.6A		43	50	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.2A		56	63	
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-1.2A		74	84	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-3.6A		11		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1.25A, V <sub>GS</sub> =0V		-0.85	-1.2	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-6V, V <sub>GS</sub> =-4.5V I <sub>D</sub> ≡-4.3A		9	20	nC
Gate-Source Charge	Q <sub>gs</sub>			1.2		
Gate-Drain Charge	Q <sub>gd</sub>			2.8		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-6V, V <sub>GS</sub> =0V f=1MHz		600		pF
Output Capacitance	C <sub>oss</sub>			280		
Reverse Transfer Capacitance	C <sub>rss</sub>			250		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-6V, R <sub>L</sub> =1.6Ω I <sub>D</sub> ≡-3.8A, V <sub>GEN</sub> =-4.5V R <sub>G</sub> =1Ω		30	55	ns
	t <sub>r</sub>			25	45	
Turn-Off Time	t <sub>d(off)</sub>			30	55	
	t <sub>f</sub>			20	40	



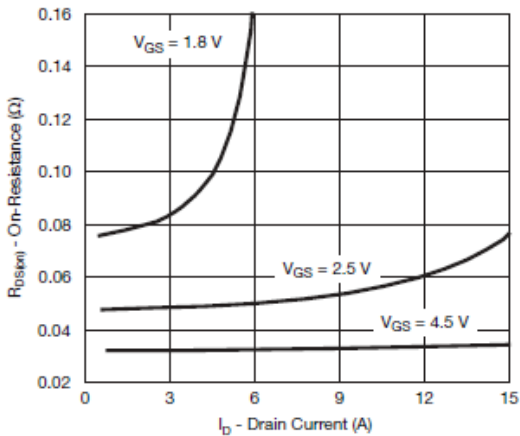
**Typical Characteristics**



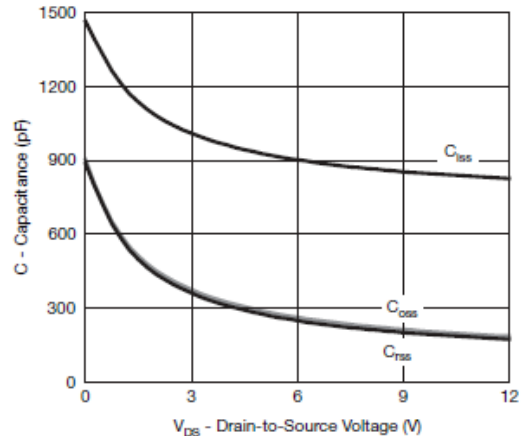
**Output Characteristics**



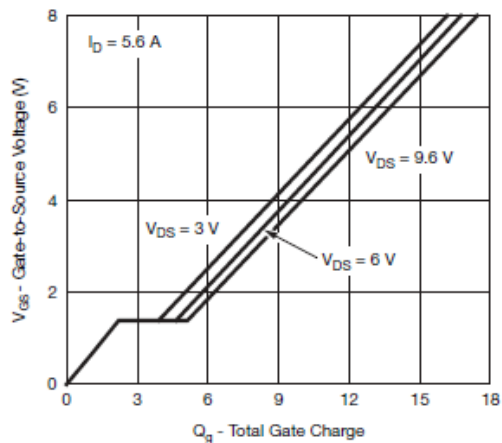
**Transfer Characteristics**



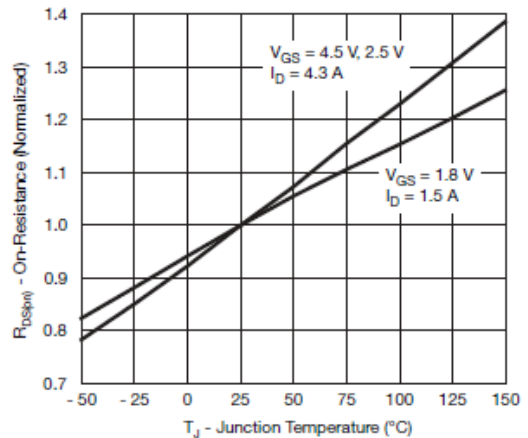
**On-Resistance vs. Drain Current and Gate Voltage**



**Capacitance**



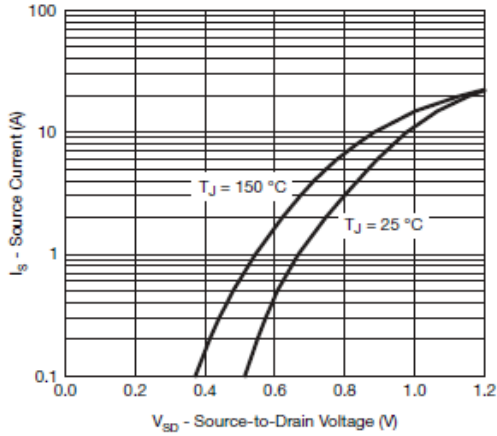
**Gate Charge**



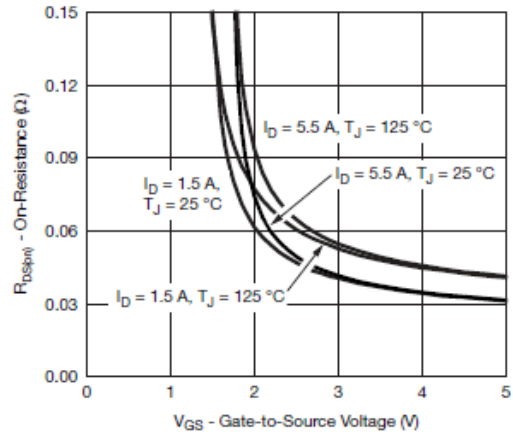
**On-Resistance vs. Junction Temperature**



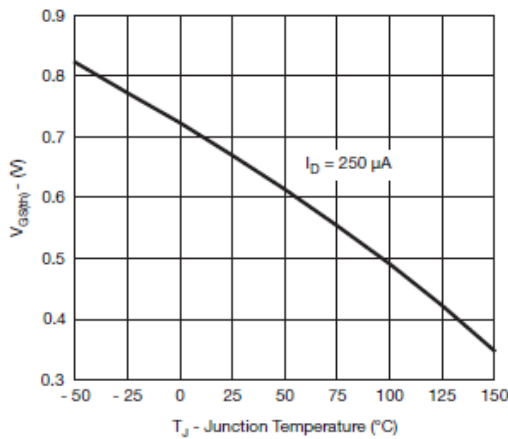
**Typical Characteristics**



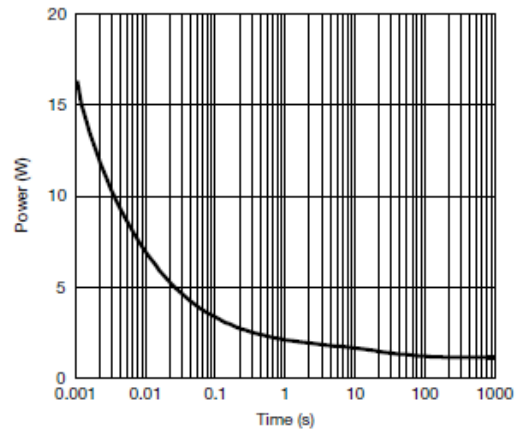
**Source-Drain Diode Forward Voltage**



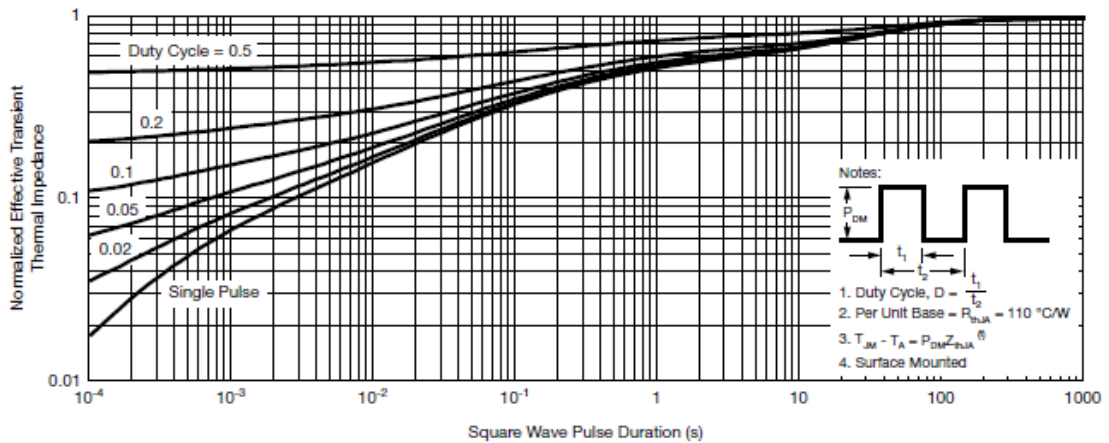
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**



**Single Pulse Power, Junction-to-Ambient**

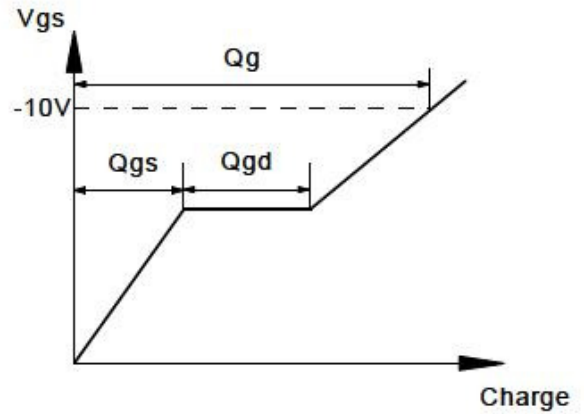
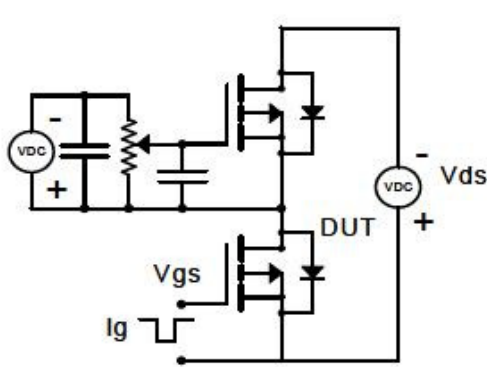


**Normalized Thermal Transient Impedance, Junction-to-Ambient**

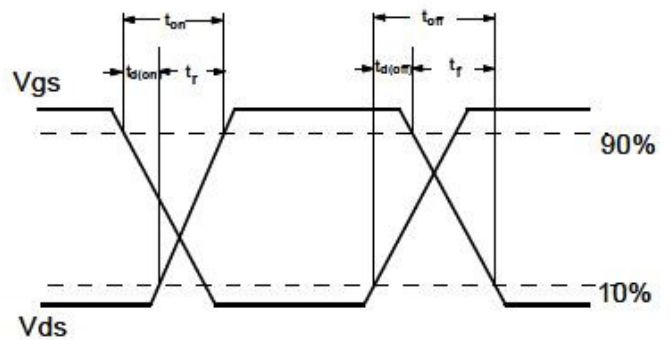
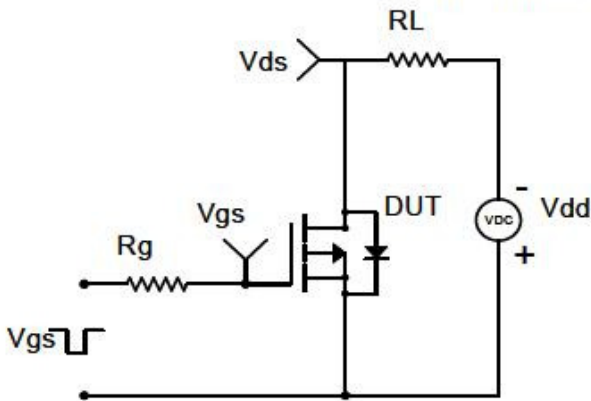


**Typical Characteristics**

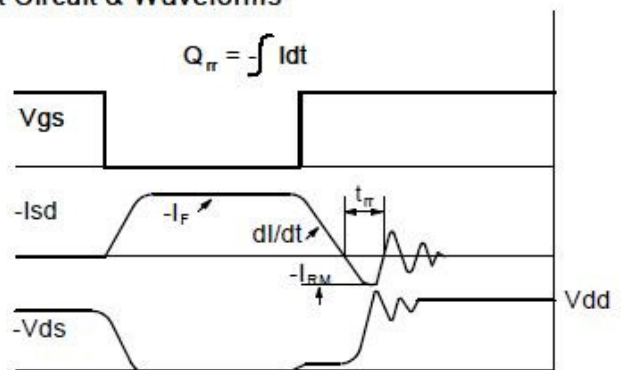
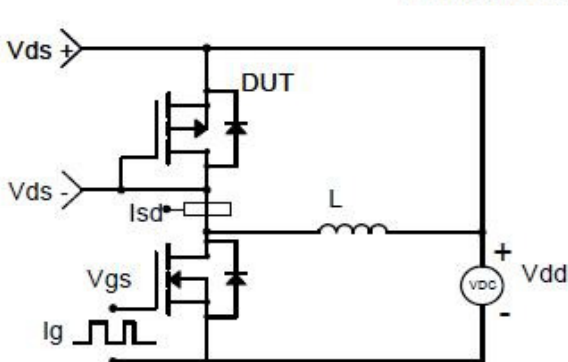
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

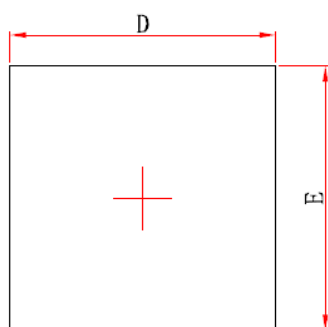


Diode Recovery Test Circuit & Waveforms

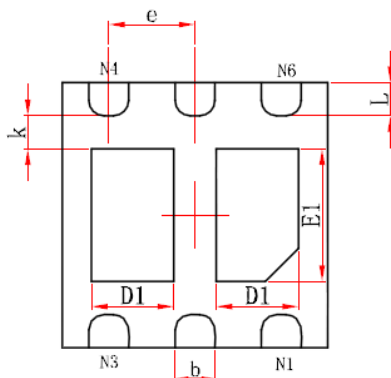




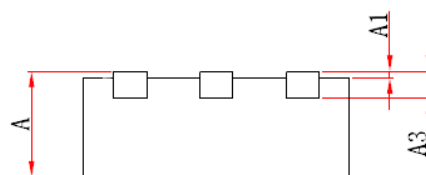
**Package Information ( DFN2X2-6L )**



**Top View**



**Bottom View**



**Side View**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.520	0.720	0.020	0.028
E1	0.900	1.100	0.035	0.043
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013

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